

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1644ign#pbf

(Engineering Calculation)

SSOP

(printed on: 2020-07-11 16:55:51)

**TOTAL MASS (g) : 0.13107**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004289	1000000	32723.0585938		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.040238	975000	306997.09375		
		Iron (Fe)	7439-89-6	0.000990	24000	7553.23632812		
		Phosphorus (P)	7723-14-0	0.000012	300	91.5543823242		
		Zinc (Zn)	7440-66-6	0.000029	700	221.25642395		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.041269</b>	<b>1000000</b>	<b>314863.15625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002831	1000000	21596.4042969		
		<b>External Plating Total:</b>				<b>0.002831</b>	<b>1000000</b>	<b>21596.4042969</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000330	1000000	2517.74560547		
<b>Internal Plating Total:</b>				<b>0.000330</b>	<b>1000000</b>	<b>2517.74560547</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001187	750000	9056.25292969		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000396	250000	3021.29443359		
<b>Die Attach Total:</b>				<b>0.001583</b>	<b>1000000</b>	<b>12077.5488281</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb Free	Resin (EP)		0.008259	103000	63012.3007812		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.071761	895000	547502.8125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000160	2000	1220.72497559		
		<b>Encapsulation Total:</b>				<b>0.080180</b>	<b>1000000</b>	<b>611735.8125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000588	1000000	4486.16455078		
					<b>TOTAL MASS (g) :</b>	<b>0.13107</b>		